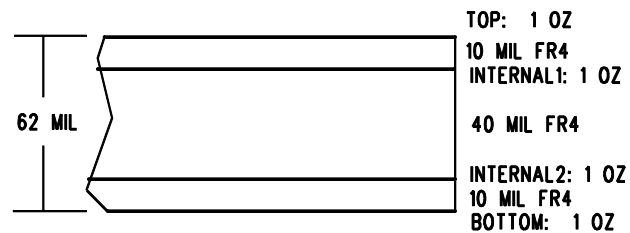


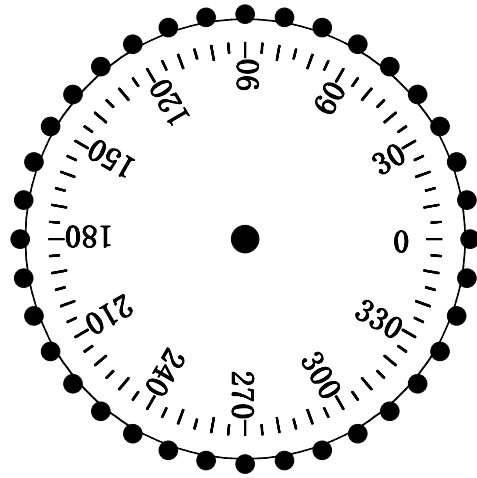
LAYER NAME	1	DRILL DRAWING
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SIZE	QTY	SYM	PLATED	TOL
85	36	+	NO	+/-0.0
125	1	X	NO	+/-0.0

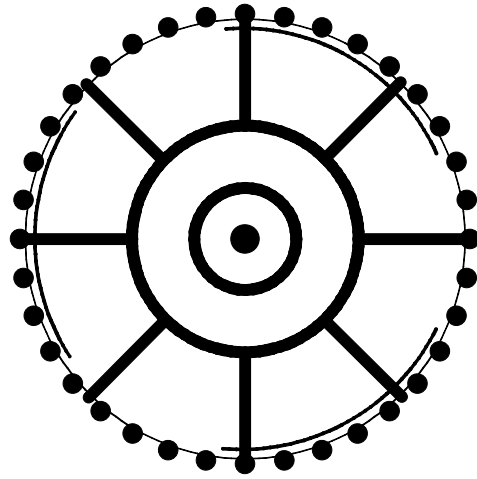
Overall Board Thickness: 62 Mil
 Soldermask Color: Black
 Drill hole tolerance: +/-3 Mil
 Copper/Spacing Clearances: 6/6 Mil
 Finish: Immersion Gold

COMPANY	TI-SVA		
PCB PART NUMBER	DIAL	REV	2
DATE	1/25/15		
NOTES			

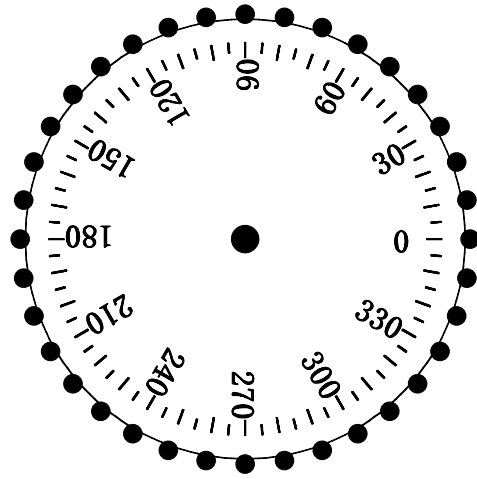




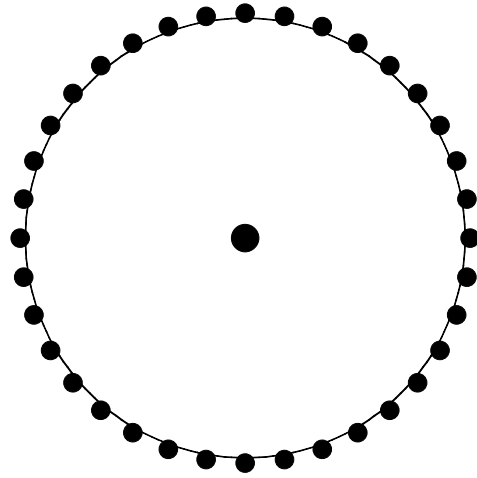
LAYER NAME	SOLDER MASK TOP
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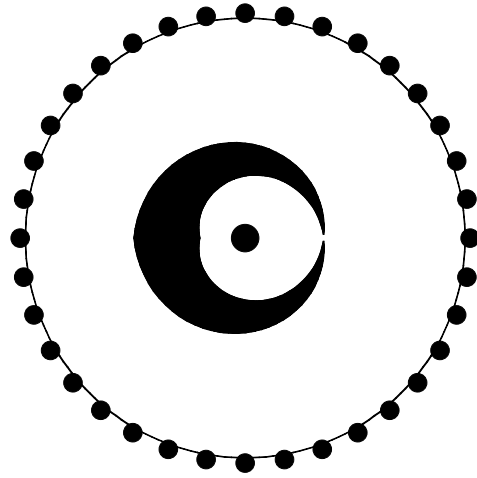
LAYER NAME	SOLDER MASK BOTTOM
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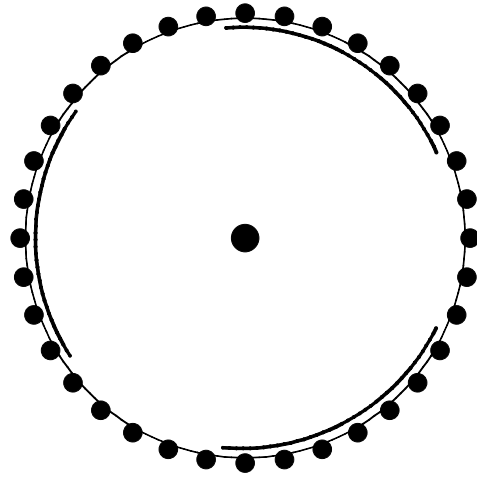
LAYER NAME	1	
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LAYER NAME	2	
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LAYER NAME	3	
------------	---	--



LAYER NAME	4	BOTTOM COMPONENT
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